Hewlett Packard Enterprise

Product End-of-Life Disassembly Instructions

Product Category: Servers
Marketing Name / Model [List multiple models if applicable.]
HPE Edgeline EL1000

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HPE products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	5
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries No	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps No	0
Cathode Ray Tubes (CRT)	No	0
Capacitors / condensers (Containing PCB/PCT)	No	0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	Depends on PSU Module	6
External electrical cables and cords		0
Gas Discharge Lamps	No	0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	No	0
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations. No	0
Components and waste containing asbestos	No	0

Item Description	Notes	Quantity of items included in product
Components, parts and materials containing refractory ceramic fibers	No	0
Components, parts and materials containing radioactive substances	No	0

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Torx Driver	T-10/15
Philps Screwdriver	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. System Board Battery (1G/10G I/O Board)

a. Remove 2 screws on rear side of Juno Chassis with T-10 Driver.
b. Slide Hood and remove 2 Black Screw with T15 Driver to detach PCIe/PXIe Baseboard Kit.
c. Remove 2 HDD Cage Screw with T10 Driver than you could

2. Capacitance

Capacitance which is inserted by operator
a. let tin touch the two pin of the capacitance
b. second, soldering tin the points with Soldering Station which set the temperature to 330
c. 10oC for L/F model , if non-L/F model, set the temperature to 300
d. 10oC, remove capacitance from PCB after tin completely melting, and then put it into Recycled Box(Remark:if capacitance which is disassembled is GND ,Set the Soldering Station(Gao Zhou)temperature to 300 �10oC, remove capacitance from PCB after tin completely melting,
e. Put it into Recycled Box
(Remark: if capacitance which is disassembled is GND, Set the Soldering Station (Gao Zhou)

3. Capacitors in 800W/500W PSU

a. 2.5 cm Pull down the lid to release the power supply from Chassis
b. Removing 2 screw on the Bottom Side with T15 Driver
c. Removing 1 screw on the Right Side with Philips Driver
d. Removing 4 screw on the Fan Module
e. Open its cover and locate the capacitors and pry from the PCB with a flat head screw driver or long nose plier and dispose of properly.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations)

Attachment 1 - System Exploding Drawing

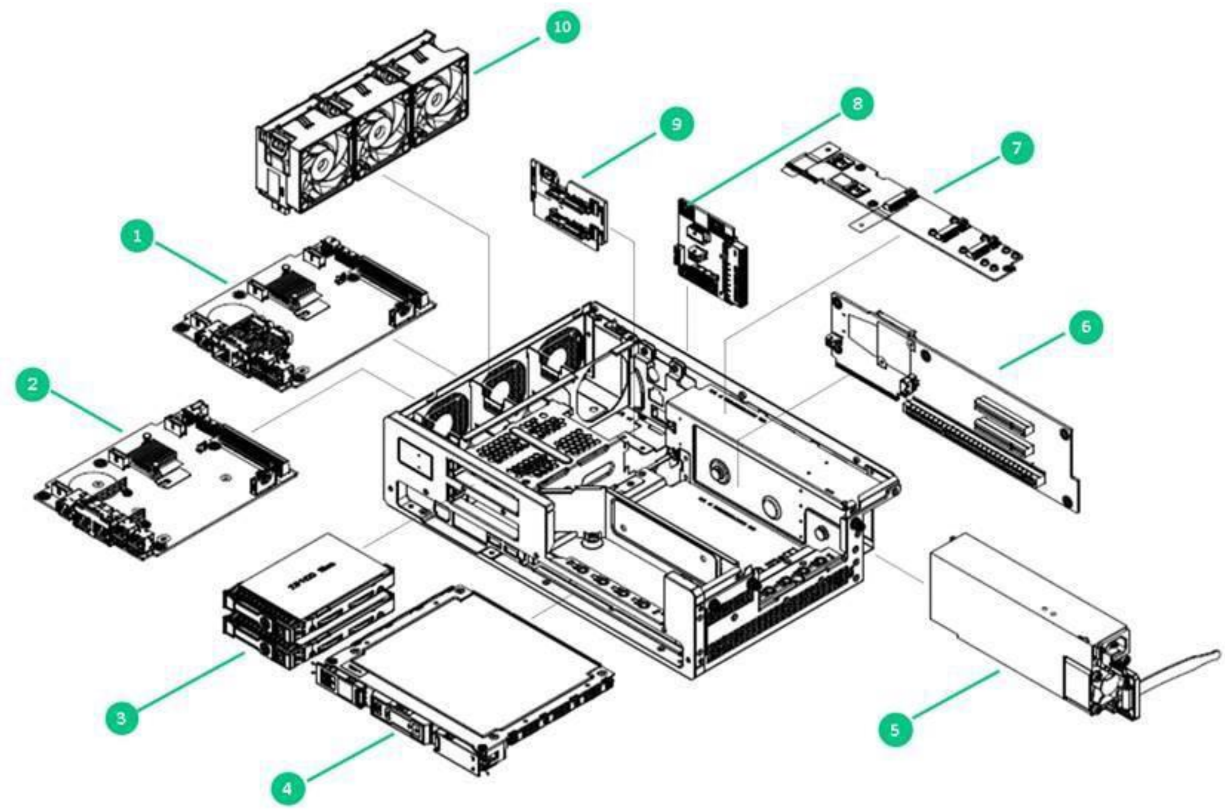
Attachment 2- System Battery Location

Attachment 3 – Remove Fan Kit

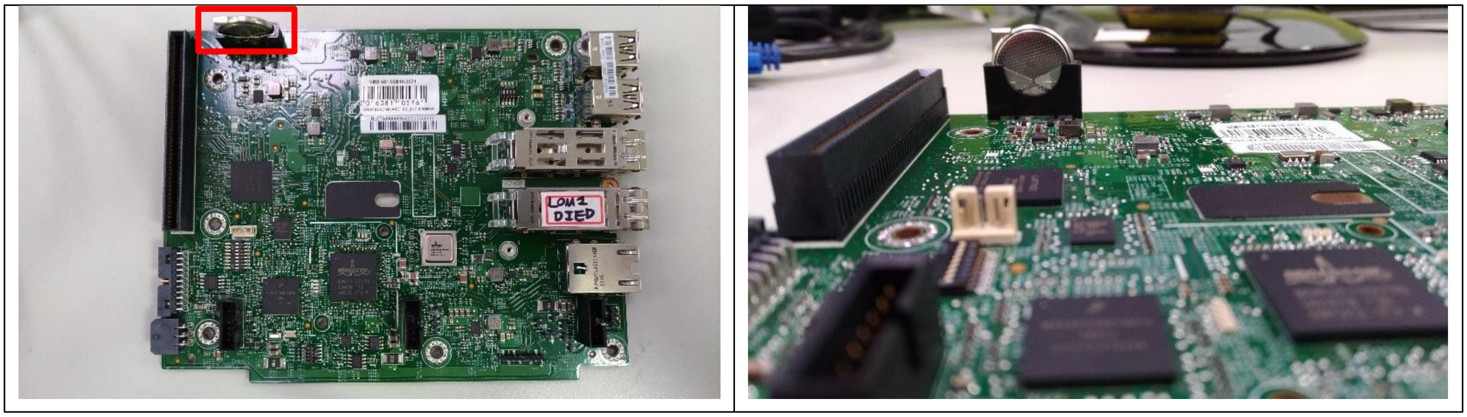
Attachment 4 - Remove 500W/800W PSU

Attachment 5 – PSU Capacitor Location

Attachment 1- Edgeline EL1000 System Exploding Drawing

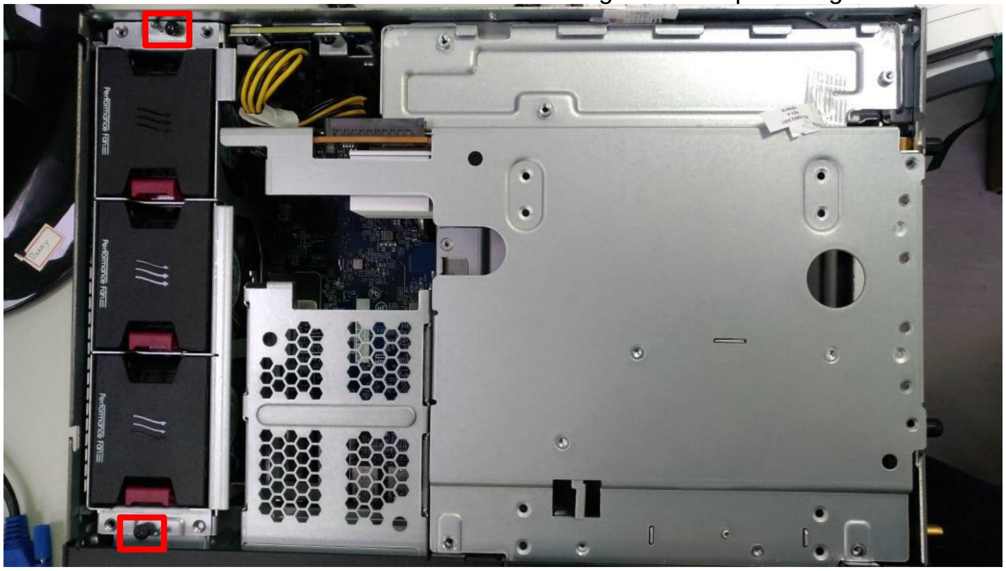


Attachment 2- System Battery Location - 10G I/O Board Location: BT1



Attachment 3- Remove Fan Kit

Remove 2 screws with T15 Driver to release the cage and lift up the cage

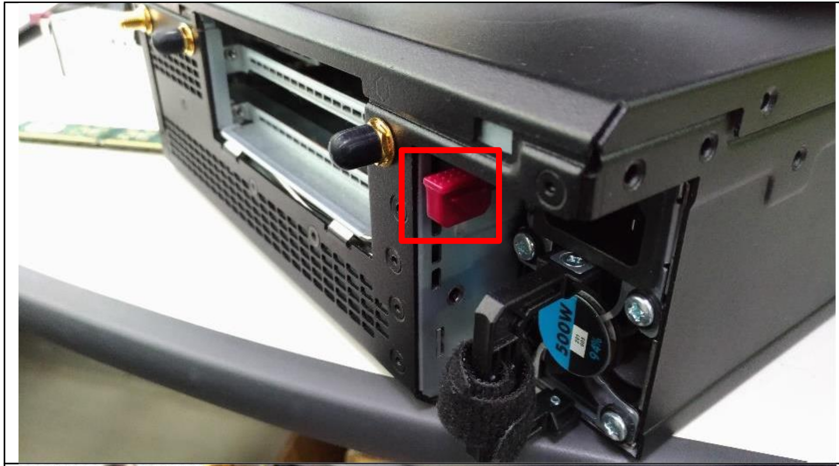


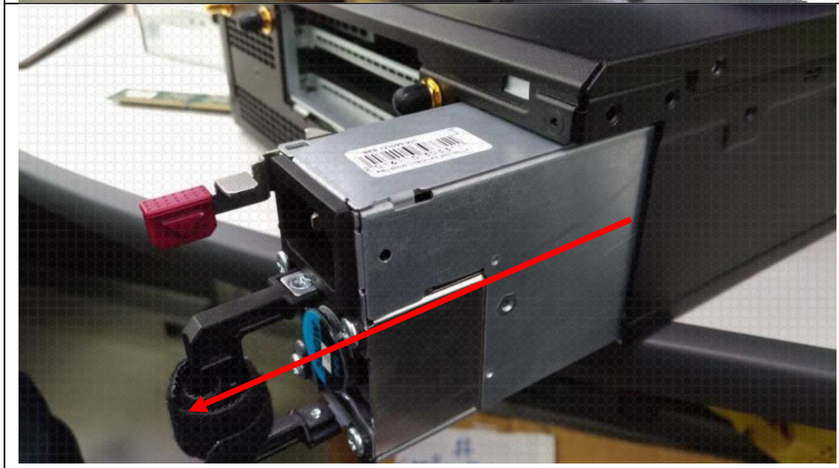
Pinch the red holder to remove the fans.

HPE instructions for this template are available at [MF877-01](MF877-01)

Attachment 4- Remove 800/500W PSU

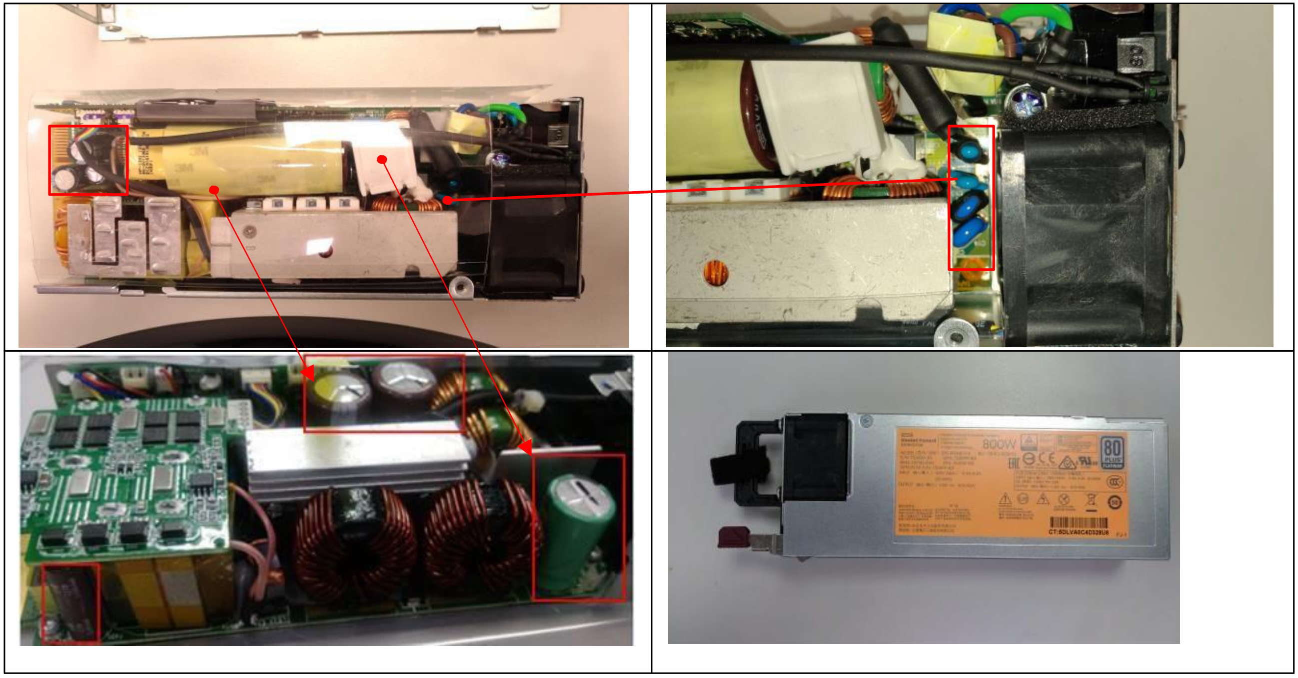
Pull down the lock and hold the holder to pulled out the module





Attachment 5-

Remove 800W PSU Capacitor Location



Remove 500W PSU Capacitor Location